

Product Change Notification - JAON-30ZGKM586

Date: 05 Nov 2015

Notification subject: CCB 1754 Final Notice: Qualification of 8390A die attach material for products available 14L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of 8390A die attach material for products available 14L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Pre Change:
3280 die attach material

Post Change:
3280 die attach material or 8390A die attach material

Impacts to Data Sheet:
None

Reason for Change:
To improve on-time delivery performance by qualifying 8390A die attach material.

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 15, 2015 (date code: 1546)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	November 2015	December 2015
Qual Report Availability	X	
Final PCN Issue Date	X	
Implementation Date	X	

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

November 5, 2015: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-30ZGKM586_Qual_Report.pdf](#)
[PCN_JAON-30ZGKM586_Affected_CPN.pdf](#)
[PCN_JAON-30ZGKM586_Affected_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
HA1086-I/SL
HA1086T-I/SL
HA1504-I/SL
HA1504T-I/SL
HA2038-I/SL
HA2089-I/SL
HA2089-I/SL108
HA2089T-I/SL
HA2089T-I/SL040
HA2089T-I/SL043
HA2089T-I/SL054
HA2089T-I/SL057
HA2089T-I/SL077
HA2089T-I/SL086
HA2089T-I/SL097
HA2089T-I/SL100
HA2089T-I/SL103
HA2089T-I/SL104
HA2089T-I/SL106
HA2089T-I/SL108
MCP2030A-I/SL
MCP2030AT-I/SL
MCP2030-I/SL
MCP2030T-I/SL
MCP2036-I/SL
MCP2036T-I/SL
MCP2120-I/SL
MCP2120T-I/SL
MCP2221-I/SL
MCP2221T-I/SL
MCP25020-E/SL
MCP25020-I/SL
MCP25020T-E/SL
MCP25020T-I/SL
MCP25025-I/SL
MCP25025T-I/SL
MCP25050-E/SL
MCP25050-I/SL
MCP25050T-E/SL
MCP25050T-I/SL
MCP25055-I/SL
MCP25055T-I/SL
MCP3004-I/SL
MCP3004T-I/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
MCP3204-BI/SL
MCP3204-CI/SL
MCP3204T-BI/SL
MCP3204T-CI/SL
MCP3302-BI/SL
MCP3302-CI/SL
MCP3302T-BI/SL
MCP3302T-CI/SL
MCP3424-E/SL
MCP3424T-E/SL
MCP3428-E/SL
MCP3428T-E/SL
MCP42010-E/SL
MCP42010-I/SL
MCP42010T-E/SL
MCP42010T-I/SL
MCP42050-E/SL
MCP42050-I/SL
MCP42050T-E/SL
MCP42050T-I/SL
MCP42100-E/SL
MCP42100-I/SL
MCP42100T-E/SL
MCP42100T-I/SL
MCP4231-103E/SL
MCP4231-104E/SL
MCP4231-502E/SL
MCP4231-503E/SL
MCP4231T-103E/SL
MCP4231T-104E/SL
MCP4231T-502E/SL
MCP4231T-503E/SL
MCP4241-103E/SL
MCP4241-104E/SL
MCP4241-502E/SL
MCP4241-503E/SL
MCP4241T-103E/SL
MCP4241T-104E/SL
MCP4241T-502E/SL
MCP4241T-503E/SL
MCP4251-103E/SL
MCP4251-104E/SL
MCP4251-502E/SL
MCP4251-503E/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
MCP4251T-103E/SL
MCP4251T-104E/SL
MCP4251T-502E/SL
MCP4251T-503E/SL
MCP4261-103E/SL
MCP4261-104E/SL
MCP4261-502E/SL
MCP4261-503E/SL
MCP4261T-103E/SL
MCP4261T-104E/SL
MCP4261T-502E/SL
MCP4261T-503E/SL
MCP4902-E/SL
MCP4902T-E/SL
MCP4912-E/SL
MCP4912T-E/SL
MCP4922-E/SL
MCP4922T-E/SL
MCP6004-E/SL
MCP6004-I/SL
MCP6004-I/SLB21
MCP6004T-E/SL
MCP6004T-I/SL
MCP6004T-I/SLB21
MCP6024-E/SL
MCP6024-I/SL
MCP6024T-E/SL
MCP6024T-I/SL
MCP6044-E/SL
MCP6044-E/SLBAA
MCP6044-I/SL
MCP6044T-E/SL
MCP6044T-E/SLBAA
MCP6044T-I/SL
MCP604-E/SL
MCP604-I/SL
MCP604T-E/SL
MCP604T-I/SL
MCP609-I/SL
MCP609T-I/SL
MCP6144-E/SL
MCP6144-I/SL
MCP6144T-E/SL
MCP6144T-I/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
MCP619-I/SL
MCP619-I/SLB21
MCP619T-I/SL
MCP619T-I/SLB21
MCP6234-E/SL
MCP6234T-E/SL
MCP6244-E/SL
MCP6244T-E/SL
MCP6274-E/SL
MCP6274-E/SLB21
MCP6274T-E/SL
MCP6274T-E/SLB21
MCP6284-E/SL
MCP6284-E/SLDAA
MCP6284T-E/SL
MCP6284T-E/SLDAA
MCP6294-E/SL
MCP6294T-E/SL
MCP6404-E/SL
MCP6404-H/SL
MCP6404T-E/SL
MCP6404T-H/SL
MCP6409-H/SL
MCP6409T-H/SL
MCP6424-E/SL
MCP6424T-E/SL
MCP6444-E/SL
MCP6444T-E/SL
MCP6474-E/SL
MCP6474T-E/SL
MCP6484-E/SL
MCP6484T-E/SL
MCP6494-E/SL
MCP6494T-E/SL
MCP6544-E/SL
MCP6544-I/SL
MCP6544T-E/SL
MCP6544T-I/SL
MCP6549-E/SL
MCP6549-I/SL
MCP6549T-E/SL
MCP6549T-I/SL
MCP6G04-E/SL
MCP6G04T-E/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
MCP6L04T-E/SL
MCP6L4T-E/SL
MCP6L74T-E/SL
MCP6L94T-E/SL
MCP6S26-I/SL
MCP6S26T-I/SL
MCP795W10-I/SL
MCP795W10T-I/SL
MCP795W11-I/SL
MCP795W11T-I/SL
MCP795W12-I/SL
MCP795W12T-I/SL
MCP795W20-I/SL
MCP795W20T-I/SL
MCP795W21-I/SL
MCP795W21T-I/SL
MCP795W22-I/SL
MCP795W22T-I/SL
MCV14A-I/SL
MCV14A-I/SL020
MCV14A-I/SL022
MCV14A-I/SL023
MCV14A-I/SL024
MCV14A-I/SL029
MCV14A-I/SL032
MCV14A-I/SL037
MCV14A-I/SL038
MCV14A-I/SL039
MCV14A-I/SL040
MCV14A-I/SL042
MCV14A-I/SL043
MCV14A-I/SL044
MCV14A-I/SL045
MCV14A-I/SL046
MCV14A-I/SL049
MCV14A-I/SL050
MCV14A-I/SL051
MCV14A-I/SL052
MCV14A-I/SL054
MCV14A-I/SL060
MCV14A-I/SL062
MCV14AT-I/SL
MCV14AT-I/SL020
MCV14AT-I/SL021

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PCN_JAON-30ZGKM586
CATALOG_PART_NBR
MCV14AT-I/SL022
MCV14AT-I/SL023
MCV14AT-I/SL024
MCV14AT-I/SL025
MCV14AT-I/SL029
MCV14AT-I/SL032
MCV14AT-I/SL035
MCV14AT-I/SL037
MCV14AT-I/SL038
MCV14AT-I/SL039
MCV14AT-I/SL040
MCV14AT-I/SL042
MCV14AT-I/SL043
MCV14AT-I/SL044
MCV14AT-I/SL045
MCV14AT-I/SL046
MCV14AT-I/SL049
MCV14AT-I/SL050
MCV14AT-I/SL051
MCV14AT-I/SL052
MCV14AT-I/SL054
MCV14AT-I/SL055
MCV14AT-I/SL057
MCV14AT-I/SL058
MCV14AT-I/SL060
MCV14AT-I/SL062
PIC16C505-04/SL
PIC16C505-04E/SL
PIC16C505-04I/SL
PIC16C505-20/SL
PIC16C505-20E/SL
PIC16C505-20I/SL
PIC16C505T-04/SL
PIC16C505T-04/SL098
PIC16C505T-04E/SL
PIC16C505T-04E/SL115
PIC16C505T-04I/SL
PIC16C505T-04I/SL060
PIC16C505T-04I/SL111
PIC16C505T-04I/SL135
PIC16C505T-04I/SL137
PIC16C505T-20/SL
PIC16C505T-20E/SL
PIC16C505T-20I/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F1455-E/SL
PIC16F1455-I/SL
PIC16F1455T-I/SL
PIC16F1503-E/SL
PIC16F1503-I/SL
PIC16F1503T-E/SL
PIC16F1503T-I/SL
PIC16F1503T-I/SL020
PIC16F1503T-I/SL034
PIC16F1503T-I/SL036
PIC16F1503T-I/SL038
PIC16F1503T-I/SL041
PIC16F1503T-I/SL046
PIC16F1574-E/SL
PIC16F1574-I/SL
PIC16F1574T-I/SL
PIC16F1575-E/SL
PIC16F1575-I/SL
PIC16F1575T-I/SL
PIC16F1613-E/SL
PIC16F1613-I/SL
PIC16F1613T-I/SL
PIC16F1614-E/SL
PIC16F1614-I/SL
PIC16F1614T-I/SL
PIC16F1615-E/SL
PIC16F1615-I/SL
PIC16F1615T-I/SL
PIC16F1703-E/SL
PIC16F1703-I/SL
PIC16F1703T-I/SL
PIC16F1704-E/SL
PIC16F1704-I/SL
PIC16F1704T-E/SL
PIC16F1704T-I/SL
PIC16F1705-E/SL
PIC16F1705-I/SL
PIC16F1705T-E/SL
PIC16F1705T-I/SL
PIC16F1764-E/SL
PIC16F1764-I/SL
PIC16F1764T-I/SL
PIC16F1765-E/SL
PIC16F1765-I/SL

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PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F1765T-I/SL
PIC16F1823-E/SL
PIC16F1823-I/SL
PIC16F1823-I/SL024
PIC16F1823-I/SLC04
PIC16F1823T-E/SL
PIC16F1823T-E/SL030
PIC16F1823T-I/SL
PIC16F1823T-I/SL024
PIC16F1823T-I/SL025
PIC16F1823T-I/SL026
PIC16F1823T-I/SLC04
PIC16F1824-E/SL
PIC16F1824-I/SL
PIC16F1824-I/SLC09
PIC16F1824T-E/SL
PIC16F1824T-I/SL
PIC16F1824T-I/SL021
PIC16F1824T-I/SL023
PIC16F1824T-I/SL024
PIC16F1824T-I/SL027
PIC16F1824T-I/SL032
PIC16F1824T-I/SLC09
PIC16F1825-E/SL
PIC16F1825-H/SL
PIC16F1825-I/SL
PIC16F1825T-E/SL
PIC16F1825T-H/SL
PIC16F1825T-I/SL
PIC16F1825T-I/SL029
PIC16F505-E/SL
PIC16F505-I/SL
PIC16F505-I/SL023
PIC16F505-I/SL033
PIC16F505-I/SL059
PIC16F505T-E/SL
PIC16F505T-I/SL
PIC16F505T-I/SL020
PIC16F505T-I/SL029
PIC16F505T-I/SL033
PIC16F505T-I/SL039
PIC16F505T-I/SL051
PIC16F505T-I/SL054
PIC16F505T-I/SL055

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F505T-I/SL056
PIC16F505T-I/SL057
PIC16F505T-I/SL058
PIC16F505T-I/SL059
PIC16F506-E/SL
PIC16F506-I/SL
PIC16F506T-I/SL
PIC16F506T-I/SL021
PIC16F506T-I/SL030
PIC16F506T-I/SL034
PIC16F506T-I/SL039
PIC16F506T-I/SL042
PIC16F506T-I/SL043
PIC16F506T-I/SL044
PIC16F506T-I/SL047
PIC16F526-E/SL
PIC16F526-I/SL
PIC16F526-I/SLC03
PIC16F526-I/SLC04
PIC16F526-I/SLC06
PIC16F526T-I/SL
PIC16F526T-I/SL026
PIC16F526T-I/SL027
PIC16F526T-I/SL030
PIC16F526T-I/SL031
PIC16F526T-I/SL033
PIC16F526T-I/SL034
PIC16F526T-I/SL053
PIC16F526T-I/SL061
PIC16F526T-I/SLC04
PIC16F526T-I/SLC06
PIC16F610-E/SL
PIC16F610-I/SL
PIC16F610T-I/SL
PIC16F616-E/SL
PIC16F616-E/SL052
PIC16F616-E/SL087
PIC16F616-H/SL
PIC16F616-I/SL
PIC16F616-I/SL063
PIC16F616-I/SL068
PIC16F616T-E/SL
PIC16F616T-E/SL040
PIC16F616T-E/SL072

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F616T-E/SL083
PIC16F616T-E/SL084
PIC16F616T-E/SL087
PIC16F616T-I/SL
PIC16F616T-I/SL029
PIC16F616T-I/SL033
PIC16F616T-I/SL038
PIC16F616T-I/SL048
PIC16F616T-I/SL050
PIC16F616T-I/SL054
PIC16F616T-I/SL055
PIC16F616T-I/SL063
PIC16F616T-I/SL064
PIC16F616T-I/SL068
PIC16F616T-I/SL069
PIC16F616T-I/SL074
PIC16F616T-I/SL077
PIC16F616T-I/SL086
PIC16F616T-I/SL089
PIC16F630-C/SL
PIC16F630-E/SL
PIC16F630-I/SL
PIC16F630-I/SL036
PIC16F630-I/SL044
PIC16F630-I/SL045
PIC16F630-I/SLC03
PIC16F630T-C/SL
PIC16F630T-E/SL
PIC16F630T-E/SL072
PIC16F630T-I/SL
PIC16F630T-I/SL026
PIC16F630T-I/SL035
PIC16F630T-I/SL043
PIC16F630T-I/SL053
PIC16F630T-I/SL066
PIC16F630T-I/SL080
PIC16F630T-I/SL081
PIC16F636-E/SL
PIC16F636-I/SL
PIC16F636T-E/SL
PIC16F636T-I/SL
PIC16F636T-I/SL022
PIC16F636T-I/SL038
PIC16F676-E/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F676-I/SL
PIC16F676-I/SL045
PIC16F676-I/SL050
PIC16F676-I/SL051
PIC16F676T-C/SL
PIC16F676T-E/SL
PIC16F676T-I/SL
PIC16F676T-I/SL028
PIC16F676T-I/SL038
PIC16F676T-I/SL044
PIC16F676T-I/SL051
PIC16F684-E/SL
PIC16F684-I/SL
PIC16F684-I/SL105
PIC16F684-I/SLC15
PIC16F684-I/SLC17
PIC16F684T-E/SL
PIC16F684T-I/SL
PIC16F684T-I/SL027
PIC16F684T-I/SL028
PIC16F684T-I/SL088
PIC16F684T-I/SL091
PIC16F684T-I/SL094
PIC16F684T-I/SL095
PIC16F684T-I/SL099
PIC16F684T-I/SL105
PIC16F684T-I/SLC15
PIC16F684T-I/SLC17
PIC16F688-E/SL
PIC16F688-I/SL
PIC16F688T-E/SL
PIC16F688T-E/SL043
PIC16F688T-I/SL
PIC16F688T-I/SL051
PIC16F688T-I/SL053
PIC16F688T-I/SL057
PIC16F688T-I/SL058
PIC16F753-E/SL
PIC16F753-I/SL
PIC16F753-I/SLC02
PIC16F753-I/SLPN1
PIC16F753-I/SLSM1
PIC16F753-I/SLSM2
PIC16F753T-I/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16F753T-I/SL020
PIC16F753T-I/SLC02
PIC16F753T-I/SLHS2
PIC16F753T-I/SLPN1
PIC16F753T-I/SLSM1
PIC16F753T-I/SLSM2
PIC16HV610-E/SL
PIC16HV610-I/SL
PIC16HV610T-I/SL
PIC16HV616-E/SL
PIC16HV616-I/SL
PIC16HV616T-E/SL
PIC16HV616T-I/SL
PIC16HV753-E/SL
PIC16HV753-I/SL
PIC16HV753T-E/SL
PIC16HV753T-I/SL
PIC16LC505-04/SL
PIC16LC505-04I/SL
PIC16LC505T-04/SL
PIC16LC505T-04I/SL
PIC16LF1503-E/SL
PIC16LF1503-E/SLC04
PIC16LF1503-I/SL
PIC16LF1503-I/SL021
PIC16LF1503T-E/SL
PIC16LF1503T-E/SLC04
PIC16LF1503T-I/SL
PIC16LF1503T-I/SL020
PIC16LF1554-E/SL
PIC16LF1554-I/SL
PIC16LF1554T-I/SL
PIC16LF1574-E/SL
PIC16LF1574-I/SL
PIC16LF1574T-I/SL
PIC16LF1575-E/SL
PIC16LF1575-I/SL
PIC16LF1575T-I/SL
PIC16LF1613-E/SL
PIC16LF1613-I/SL
PIC16LF1613T-I/SL
PIC16LF1614-E/SL
PIC16LF1614-I/SL
PIC16LF1614T-I/SL

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Affected Catalog Part Numbers (CPN)

PCN_JAON-30ZGKM586
CATALOG_PART_NBR
PIC16LF1615-E/SL
PIC16LF1615-I/SL
PIC16LF1615T-I/SL
PIC16LF1703-E/SL
PIC16LF1703-I/SL
PIC16LF1703T-I/SL
PIC16LF1704-E/SL
PIC16LF1704-I/SL
PIC16LF1704T-I/SL
PIC16LF1705-E/SL
PIC16LF1705-I/SL
PIC16LF1705T-I/SL
PIC16LF1764-E/SL
PIC16LF1764-I/SL
PIC16LF1764T-I/SL
PIC16LF1765-E/SL
PIC16LF1765-I/SL
PIC16LF1765T-I/SL
PIC16LF1823-E/SL
PIC16LF1823-I/SL
PIC16LF1823-I/SLC03
PIC16LF1823T-E/SL
PIC16LF1823T-I/SL
PIC16LF1823T-I/SL023
PIC16LF1823T-I/SLC03
PIC16LF1824-E/SL
PIC16LF1824-I/SL
PIC16LF1824-I/SLC01
PIC16LF1824T-E/SL
PIC16LF1824T-I/SL
PIC16LF1824T-I/SL026
PIC16LF1824T-I/SLC01
PIC16LF1825-E/SL
PIC16LF1825-E/SLC02
PIC16LF1825-I/SL
PIC16LF1825T-E/SL
PIC16LF1825T-E/SLC02
PIC16LF1825T-I/SL
PIC16LF1825T-I/SL020
PIC16LF1825T-I/SL022



MICROCHIP

**QUALIFICATION REPORT
RELIABILITY LABORATORY**

PCN #: JAON-30ZGKM586

**Date
September 29, 2015**

**Qualification of 8390A die attach material for products
available 14L SOIC package using palladium coated copper
wire (PdCu) bond wire at MTAI assembly site**

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MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose Qualification of 8390A die attach material for products available 14L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site

CCB No. 1754

MOW NO.	MTAI161702792.000	MTAI161702793.000	MTAI161702791.000
MP CODE	ABBX17D3XA00	A7AZ57D3XA04	ABAB2TD3XB12
WAFER LOT	MCP6004-I/SL	PIC16C505-04I/SL	MCP604T-I/SL
TRACE CODE	15306CS	15306CT	15306CR
Bonding No.	A-055805 Rev. A	A-054204 Rev. B	A-054244 Rev. A

Package

Type	14L SOIC	14L SOIC	14L SOIC
Package size	150 mils	150 mils	150 mils
Die thickness	15 mils	15 mils	15 mils
Die size	43.30 x 57.20 mils	76.90 x 94.10 mils	41.10 x 40.20 mils

Lead Frame

Paddle size	95 x 155 mils	95 x 155 mils	95 x 155 mils
Material	CDA194	CDA194	CDA194
Surface	Ag spot	Ag spot	Ag spot
Process	Stamp	Stamp	Stamp
Lead Lock	No	No	No
Part Number	10101411	10101411	10101411

Die attach material

Epoxy	8390A	8390A	8390A
Wire	PdCu	PdCu wire	PdCu wire
Mold Compound	G600V	G600V	G600V
Plating Composition	Matte Tin	Matte Tin	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI161702792.000	TMPE215487263.100	15306CS
MTAI161702793.000	TMPE216048989.C00	15306CT
MTAI161702791.000	TMPE216059162.800	15306CR

Result

Pass Fail _____

14L SOIC (.150") assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

Prepared By: Thinnapol Date: September 29, 2015 (Sr. Reliability Engineer)

(Mr. Thinnapol Nakkasun)

Approved By: Som Date: September 29, 2015 (Reliability Manager)

(Mr. Somnuek Thongprasert)

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD- 020D	135	0/135	Pass	

Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test :+25°C and 85°C System: ETS300	JESD22- A113	693(0)	693	Pass	Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 85°C System: ETS300			0/693		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 85°C System: ETS300	JESD22- A104	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
UNBIASED-HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System:ETS300	JESD22- A118	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22- A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C and 85°C System: ETS300		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB Electrical Test : +25°C and 85°C System: ETS300	JESD22- A103		135		45 units/ lot
			135(0)	0/135	Pass	
Bond Strength	Wire Pull (> 3.0 grams)	M2011	30 (0) Wires	0/30	Pass	
Data Assembly	Bond Shear (>15.00 grams)	JESD22 -B116	30 (0) bonds	0/30	Pass	